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Timothy H. Daubenspeck et al.

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## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
A.S.	5,659,201	8/1997	Wollesen			
	5,447,887	9/1995	Filipiak et al.			
	5,273,920	12/1993	Kwasnick et al.			
	4,198,744	4/1980	Nicolay			

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

A.S.		IBM Technical Disclosure Bulletin, Vol. 32, No. 3A, August 1989, FUSE STRUCTURE FOR WIDE FUSE MATERIALS CHOICE, pages 438-439
A.S.		SILICON NITRIDE COATINGS ON COPPER, Audisio et al., Vol. 119, No. 4, April 1972, Electrochemical Society, pages 408-411

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